

### Thyristor Modules

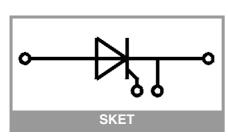
### SKET 741/22 E

#### Features

- Precious metal pressure contacts for high reliability
- Thyristor with amplifying gate
- UL recognized, file no. E 63 532

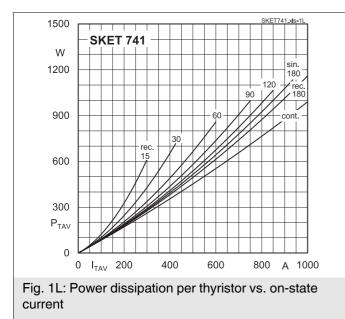
#### **Typical Applications\***

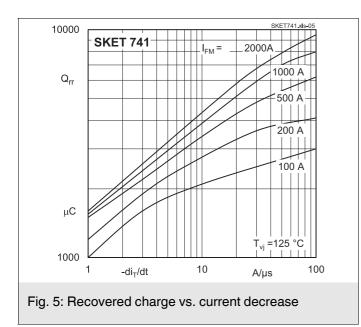
- DC motor control (e. g. for machine tools)
- Temperature control (e. g. for ovens, chemical processes)
- Softstart application

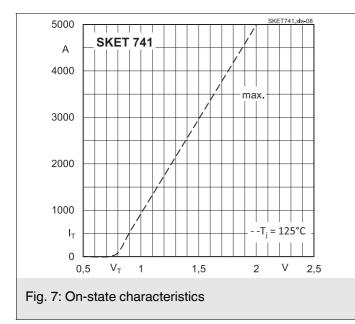


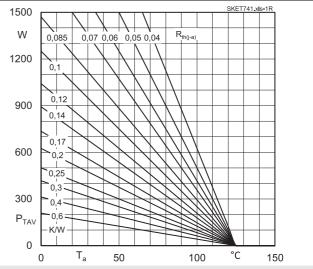
Absolute	Maximum Rating	s			
Symbol	Conditions		Values	Unit	
Chip					
I <sub>T(AV)</sub>	sinus 180°	T <sub>c</sub> = 85 °C	819	Α	
		T <sub>c</sub> = 100 °C	564	А	
I <sub>TRMS</sub>	continuous operation		1500	А	
I <sub>TSM</sub>	- 10 ms	T <sub>j</sub> = 25 °C	30000	А	
		T <sub>j</sub> = 125 °C	26500	А	
i <sup>2</sup> t	10 ms	T <sub>j</sub> = 25 °C	4500000	A <sup>2</sup> s	
		T <sub>j</sub> = 125 °C	3500000	A <sup>2</sup> s	
V <sub>RSM</sub>			2300	V	
V <sub>RRM</sub>			2200	V	
V <sub>DRM</sub>			2200	V	
(di/dt) <sub>cr</sub>			200	A/μs	
(dv/dt) <sub>cr</sub>			1000	V/µs	
Tj			-40 125	°C	
Module	·			÷	
T <sub>stg</sub>			-40 130	°C	
V <sub>isol</sub>	a.c.; 50 Hz; r.m.s.	1 min	3000	V	
		1 s	3600	V	

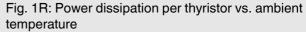
Characte	eristics					
Symbol	Conditions	min.	typ.	max.	Unit	
Chip						
V <sub>T</sub>	T <sub>j</sub> = 125 °C, I <sub>T</sub> = 3000 A				1.51	V
V <sub>T(TO)</sub>	T <sub>j</sub> = 125 °C				0.82	V
r <sub>T</sub>	T <sub>j</sub> = 125 °C				0.17	mΩ
I <sub>DD</sub> ;I <sub>RD</sub>	$T_j = 125 \ ^\circ C, V_{DD} = V_{DRM}; V_{RD} = V_{RRM}$				150	mA
t <sub>gd</sub>	$T_j = 25 \text{ °C}, I_G = 1 \text{ A}, di_G/dt = 1 \text{ A}/\mu \text{s}$				4	μs
tq				350		μs
I <sub>H</sub>	$T_j = 25 \ ^{\circ}C$				500	mA
I <sub>L</sub>	$T_j = 25 \ ^{\circ}C, R_G = 33 \ \Omega$				2500	mA
V <sub>GT</sub>	$T_{j} = 25 \ ^{\circ}C, \ d.c.$		2.2			V
I <sub>GT</sub>	$T_{j} = 25 \ ^{\circ}C, \ d.c.$		250			mA
$V_{GD}$	T <sub>j</sub> = 125 °C, d.c.				0.25	V
I <sub>GD</sub>	T <sub>j</sub> = 125 °C, d.c.				10	mA
R <sub>th(j-c)</sub>	cont.	per chip			0.0405	K/W
		per module			0.0405	K/W
$R_{\text{th(j-c)}}$	sin. 180°	per chip			0.042	K/W
		per module			0.042	K/W
$R_{th(j-c)}$	- rec. 120°	per chip			0.043	K/W
		per module			0.043	K/W
Module						
R <sub>th(c-s)</sub>	chip				0.015	K/W
	module				0.015	K/W
Ms	to heatsink M6		5.1		6.9	Nm
M <sub>t</sub>	to terminal M12		16.2		19.8	Nm
а					5 * 9,81	m/s²
w				1950		g











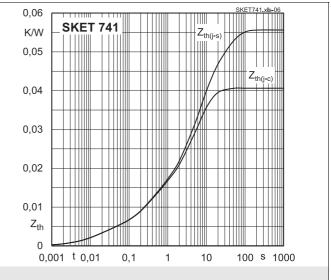


Fig. 6: Transient thermal impedance vs. time

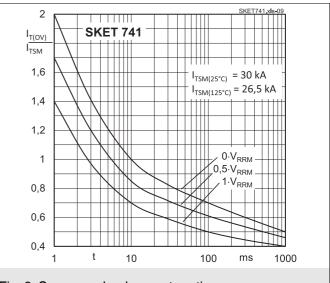
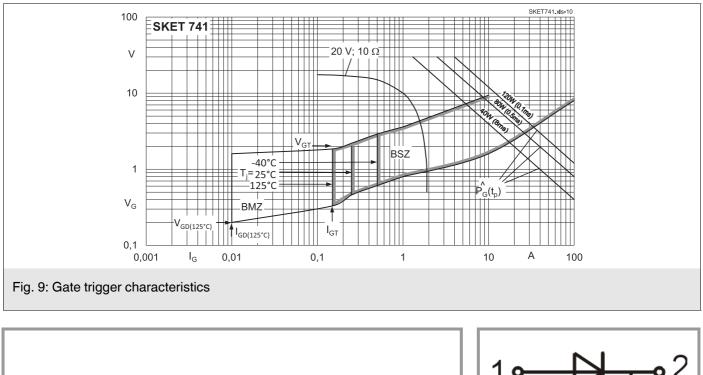
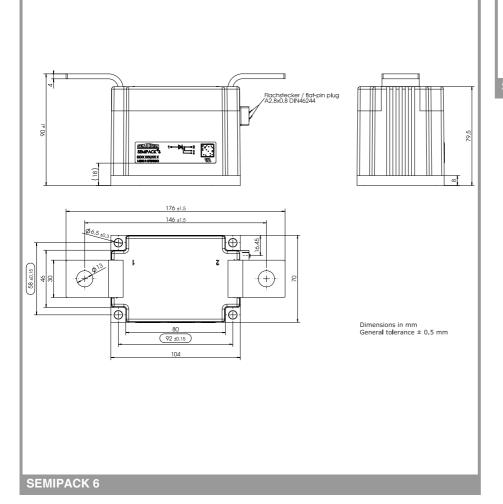
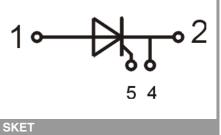


Fig. 8: Surge overload current vs. time







This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

### \*IMPORTANT INFORMATION AND WARNINGS

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